

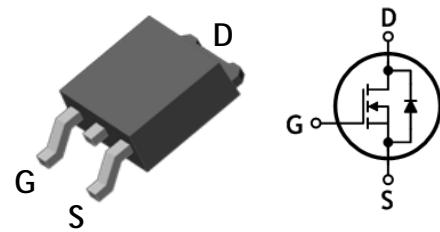
DC-DC CONVERTER APPLICATION  
HIGH VOLTAGE SWITCHING APPLICATIONS

**Features**

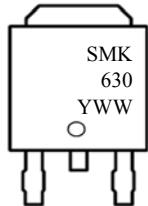
- High Voltage :  $BV_{DSS}=200V$ (Min.)
- Low  $C_{rss}$  :  $C_{rss}=24pF$ (Typ.)
- Low gate charge :  $Q_g=12nC$ (Typ.)
- Low  $R_{DS(on)}$  :  $R_{DS(on)}=0.4\Omega$ (Max.)

**Ordering Information**

Type No.	Marking	Package Code
SMK630D	SMK630	TO-252



TO-252

**Marking Diagram**


Column 1,2 : Device Code  
Column 3 : Production Information  
e.g.) YWW  
-. YWW : Date Code (year, week)

**Absolute maximum ratings ( $T_c=25^\circ C$  unless otherwise noted)**

Characteristic	Symbol		Rating	Unit
Drain-source voltage	$V_{DSS}$		200	V
Gate-source voltage	$V_{GSS}$		$\pm 30$	V
Drain current (DC) *	$I_D$	$(T_c=25^\circ C)$	9	A
		$(T_c=100^\circ C)$	5.7	A
Drain current (Pulsed) *	$I_{DM}$		36	A
Power dissipation	$P_D$		45	W
Avalanche current (Single) ②	$I_{AS}$		9	A
Single pulsed avalanche energy ②	$E_{AS}$		232	mJ
Avalanche current (Repetitive) ①	$I_{AR}$		9	A
Repetitive avalanche energy ①	$E_{AR}$		9.5	mJ
Junction temperature	$T_J$		150	$^\circ C$
Storage temperature range	$T_{stg}$		-55~150	

\* Limited by maximum junction temperature

Characteristic	Symbol	Typ.	Max.	Unit
Thermal resistance	Junction-case $R_{th(J-C)}$	-	2.77	$^\circ C/W$
	Junction-ambient $R_{th(J-A)}$	-	50	

\*\* When mounted on the minimum pad size recommended (PCB Mount)

**Electrical Characteristics ( $T_C=25^\circ\text{C}$  unless otherwise noted)**

Characteristic	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Drain-source breakdown voltage	$\text{BV}_{\text{DSS}}$	$I_D=250\mu\text{A}, V_{GS}=0$	200	-	-	V
Gate threshold voltage	$V_{GS(\text{th})}$	$I_D=250\mu\text{A}, V_{DS}=V_{GS}$	2.0	-	4.0	V
Drain-source cut-off current	$I_{\text{DSS}}$	$V_{DS}=200\text{V}, V_{GS}=0\text{V}$	-	-	1	$\mu\text{A}$
Gate leakage current	$I_{\text{GSS}}$	$V_{DS}=0\text{V}, V_{GS}=\pm 30\text{V}$	-	-	$\pm 100$	nA
Drain-source on-resistance ④	$R_{DS(\text{ON})}$	$V_{GS}=10\text{V}, I_D=4.5\text{A}$	-	0.34	0.40	$\Omega$
Forward transfer conductance ④	$g_{fs}$	$V_{DS}=10\text{V}, I_D=4.5\text{A}$	-	5.5	-	S
Input capacitance	$C_{iss}$	$V_{GS}=0\text{V}, V_{DS}=25\text{V}, f=1\text{MHz}$	-	420	525	pF
Output capacitance	$C_{oss}$		-	99	128	
Reverse transfer capacitance	$C_{rss}$		-	24	28	
Turn-on delay time	$t_{d(on)}$	$V_{DD}=100\text{V}, I_D=9\text{A}$ $R_G=25\Omega$	-	11	-	ns
Rise time	$t_r$		-	92	-	
Turn-off delay time	$t_{d(off)}$		-	70	-	
Fall time	$t_f$		-	72	-	
Total gate charge	$Q_g$	$V_{DS}=160\text{V}, V_{GS}=10\text{V}$ $I_D=9\text{A}$	-	12	17	nC
Gate-source charge	$Q_{gs}$		-	2.4	-	
Gate-drain charge	$Q_{gd}$		(3)(4)	-	3.5	-

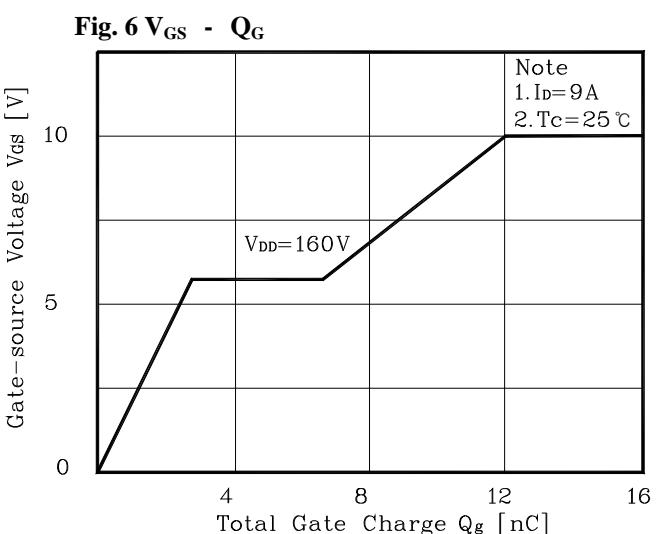
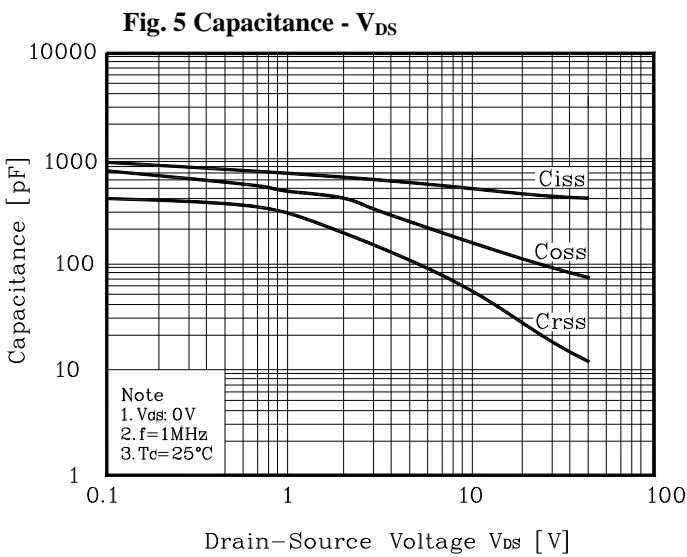
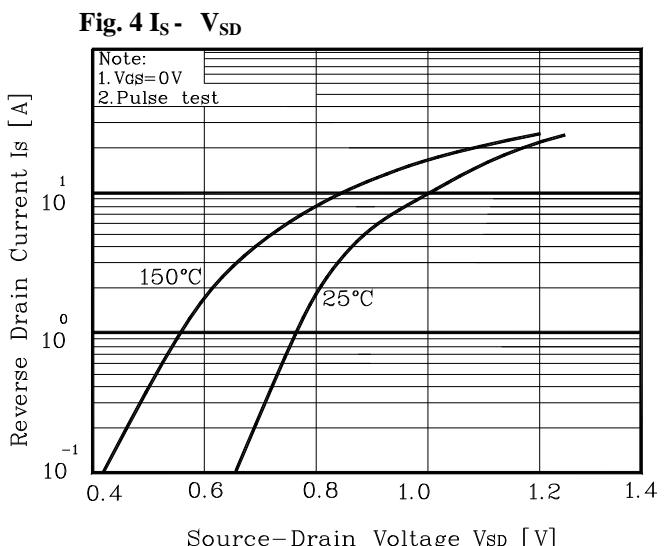
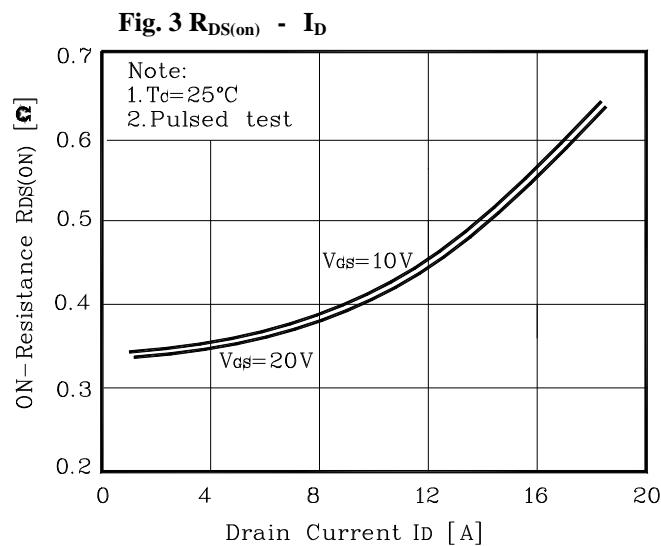
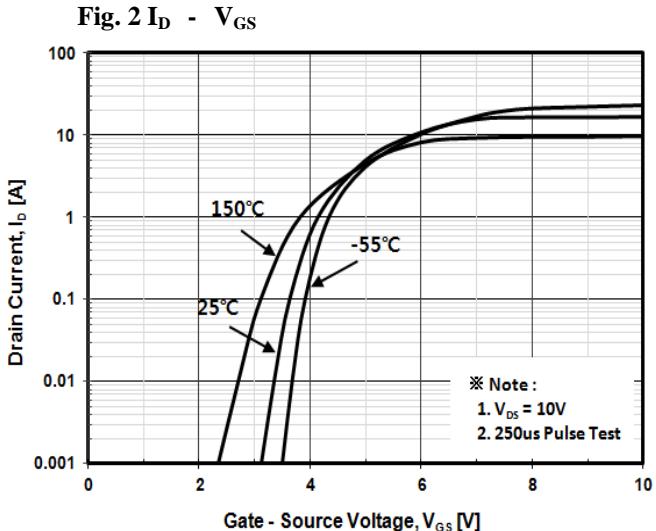
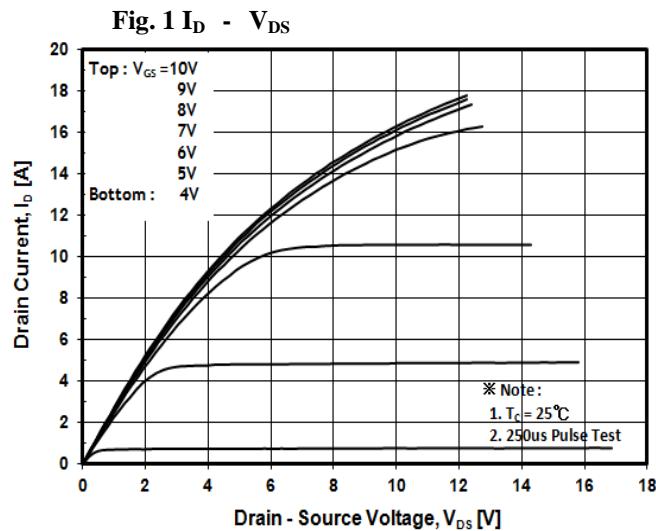
**Source-Drain Diode Ratings and Characteristics ( $T_C=25^\circ\text{C}$  unless otherwise noted)**

Characteristic	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Source current (DC)	$I_S$	Integral reverse diode in the MOSFET	-	-	9	A
Source current (Pulsed) ①	$I_{SM}$		-	-	36	
Forward voltage ④	$V_{SD}$	$V_{GS}=0\text{V}, I_S=9\text{A}$	-	-	1.4	V
Reverse recovery time	$t_{rr}$	$I_S=9\text{A}, V_{GS}=0\text{V}$ $dI_F/dt=100\text{A}/\mu\text{s}$	-	158	-	ns
Reverse recovery charge	$Q_{rr}$		-	0.97	-	$\mu\text{C}$

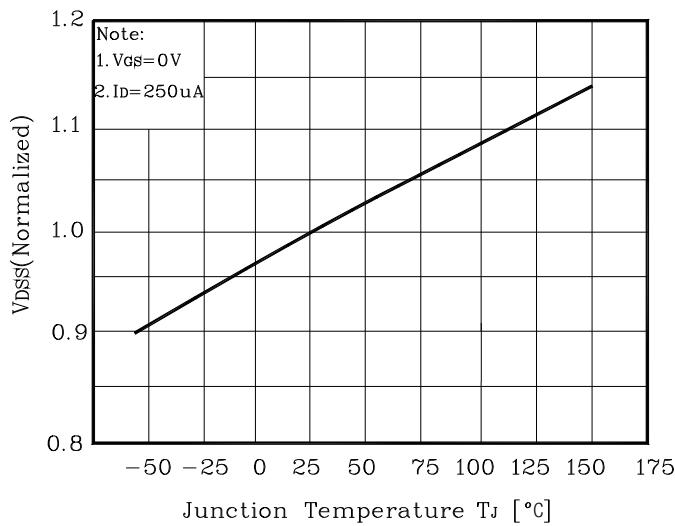
Note :

- ① Repetitive rating : Pulse width limited by maximum junction temperature
- ②  $L=4.3\text{mH}, I_{AS}=9\text{A}, V_{DD}=50\text{V}, R_G=25\Omega$ , Starting  $T_J=25^\circ\text{C}$
- ③ Pulse Test : Pulse width  $\leq 300\text{us}$ , Duty cycle  $\leq 2\%$
- ④ Essentially independent of operating temperature

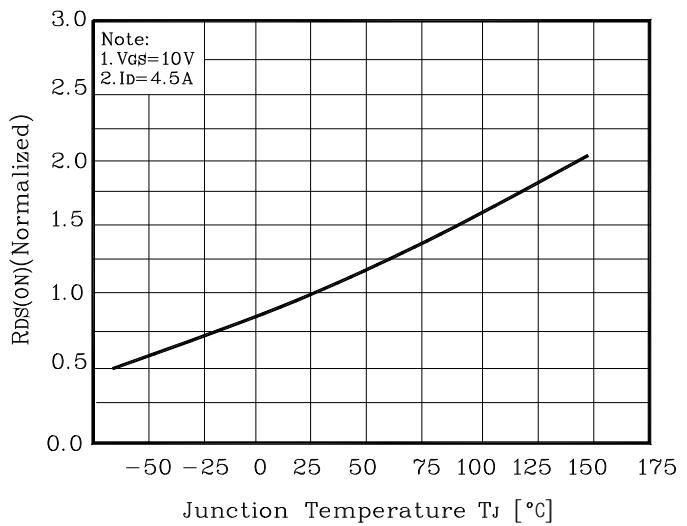
## Typical Characteristic Curves



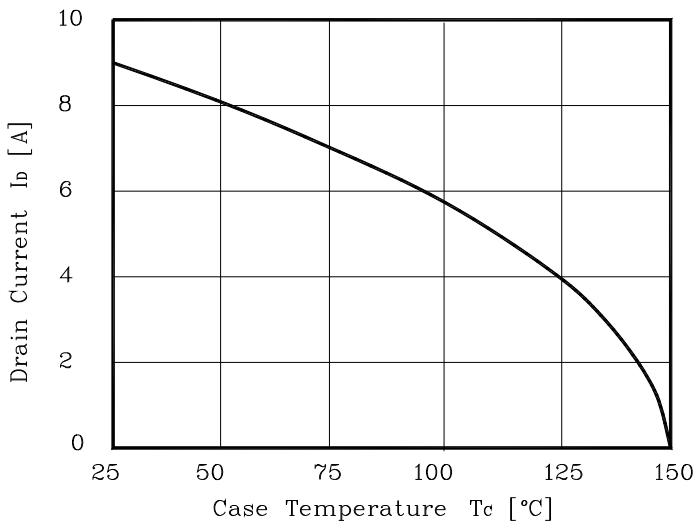
**Fig. 7  $V_{DSS}$  -  $T_J$**



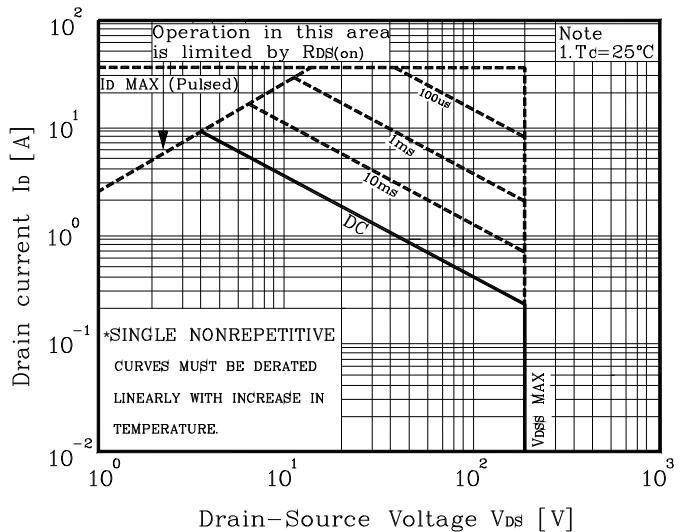
**Fig. 8  $R_{DS(on)}$  -  $T_J$**



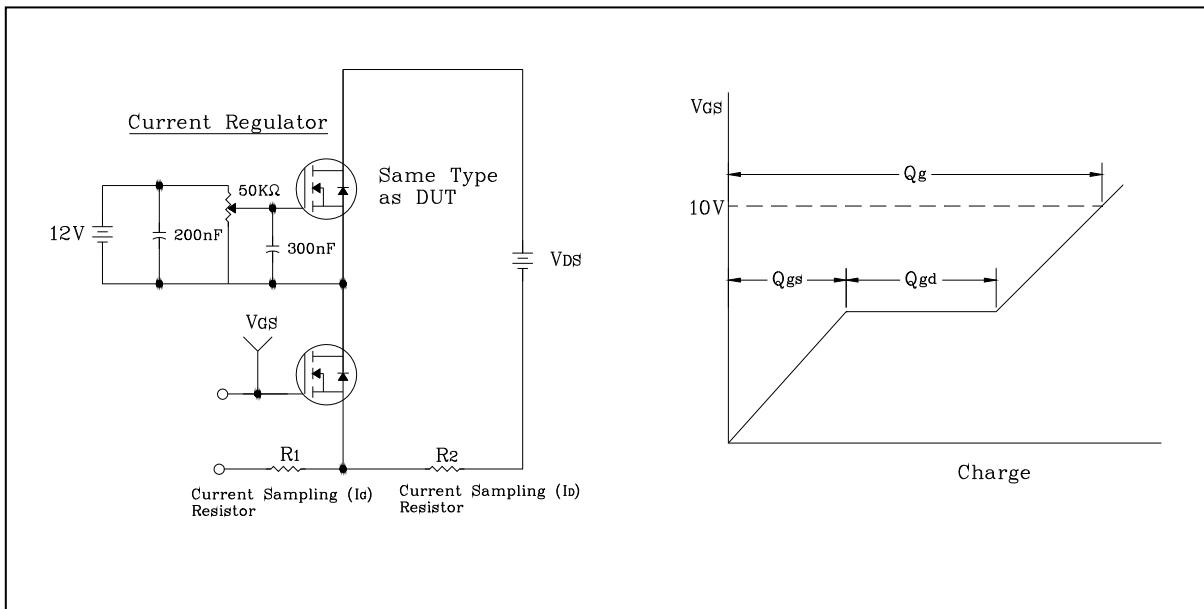
**Fig. 9  $I_D$  -  $T_C$**



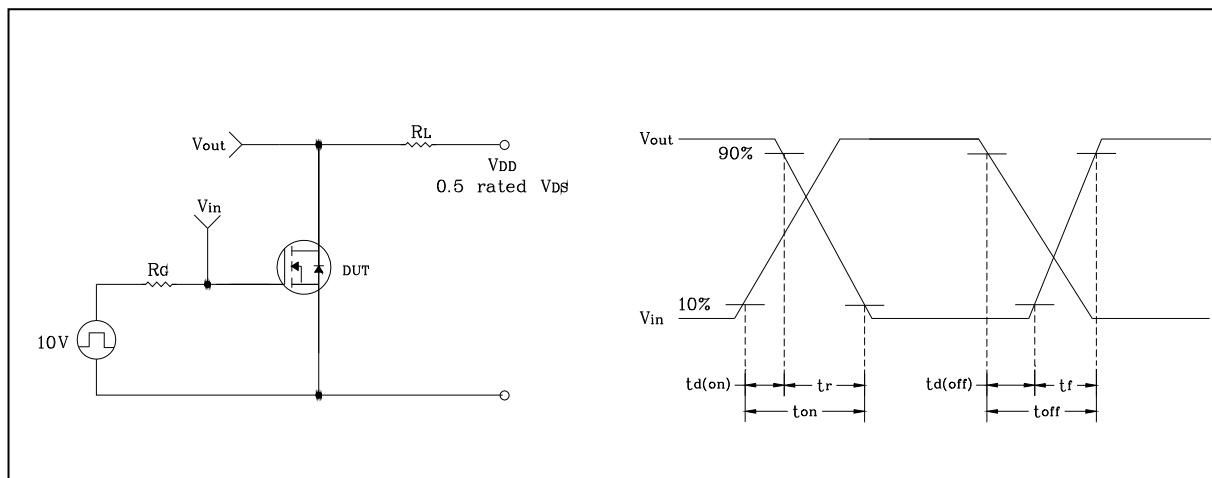
**Fig. 10 Safe Operating Area**



**Fig. 11 Gate Charge Test Circuit & Waveform**



**Fig. 12 Resistive Switching Test Circuit & Waveform**



**Fig. 13 E<sub>AS</sub> Test Circuit & Waveform**

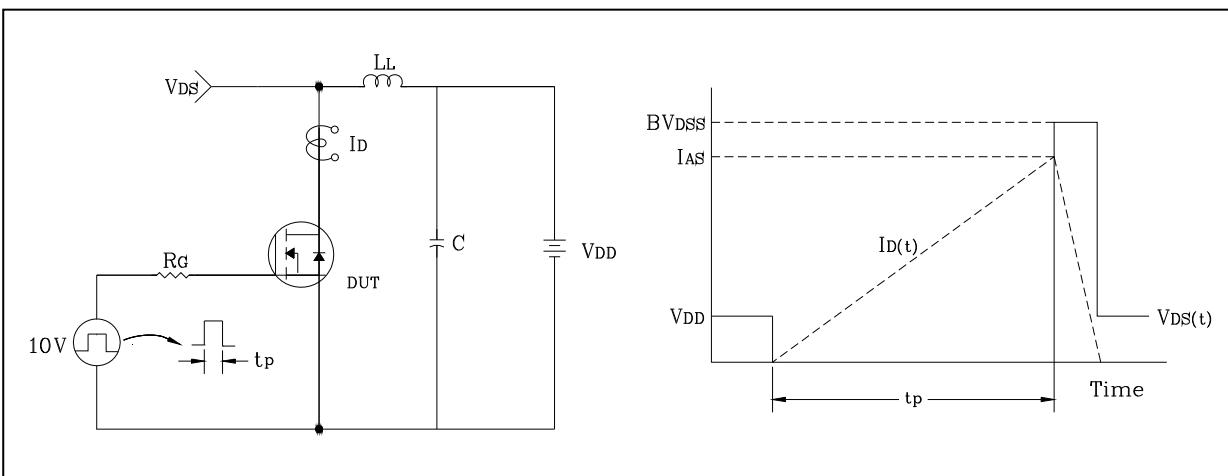
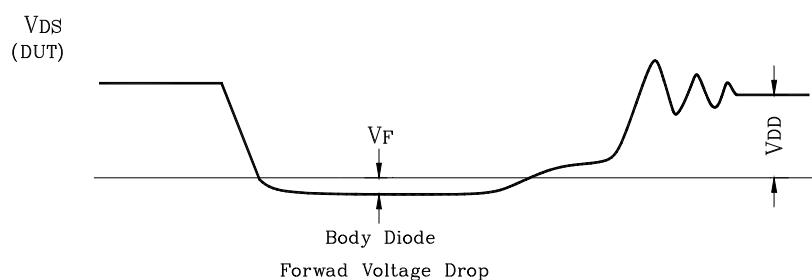
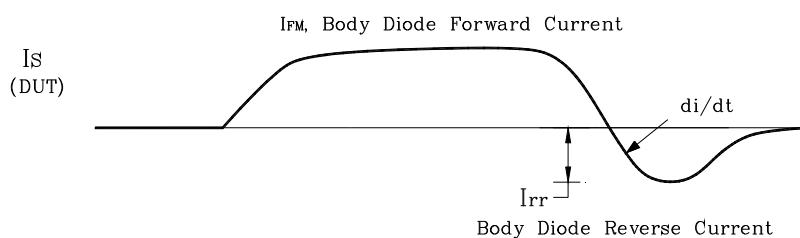
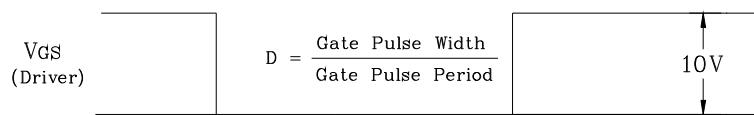
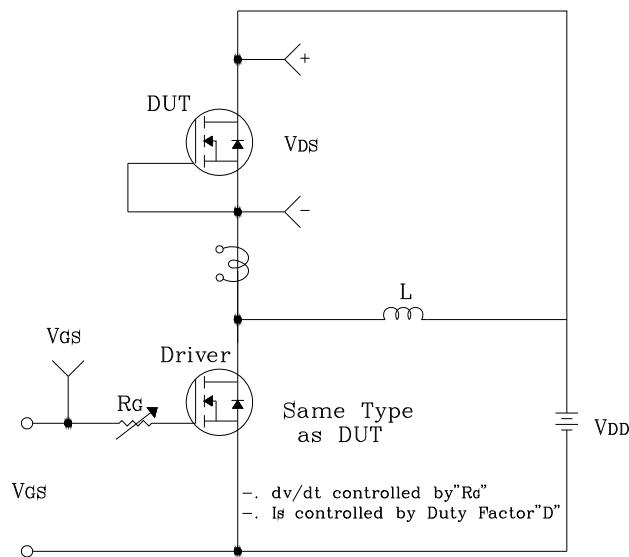
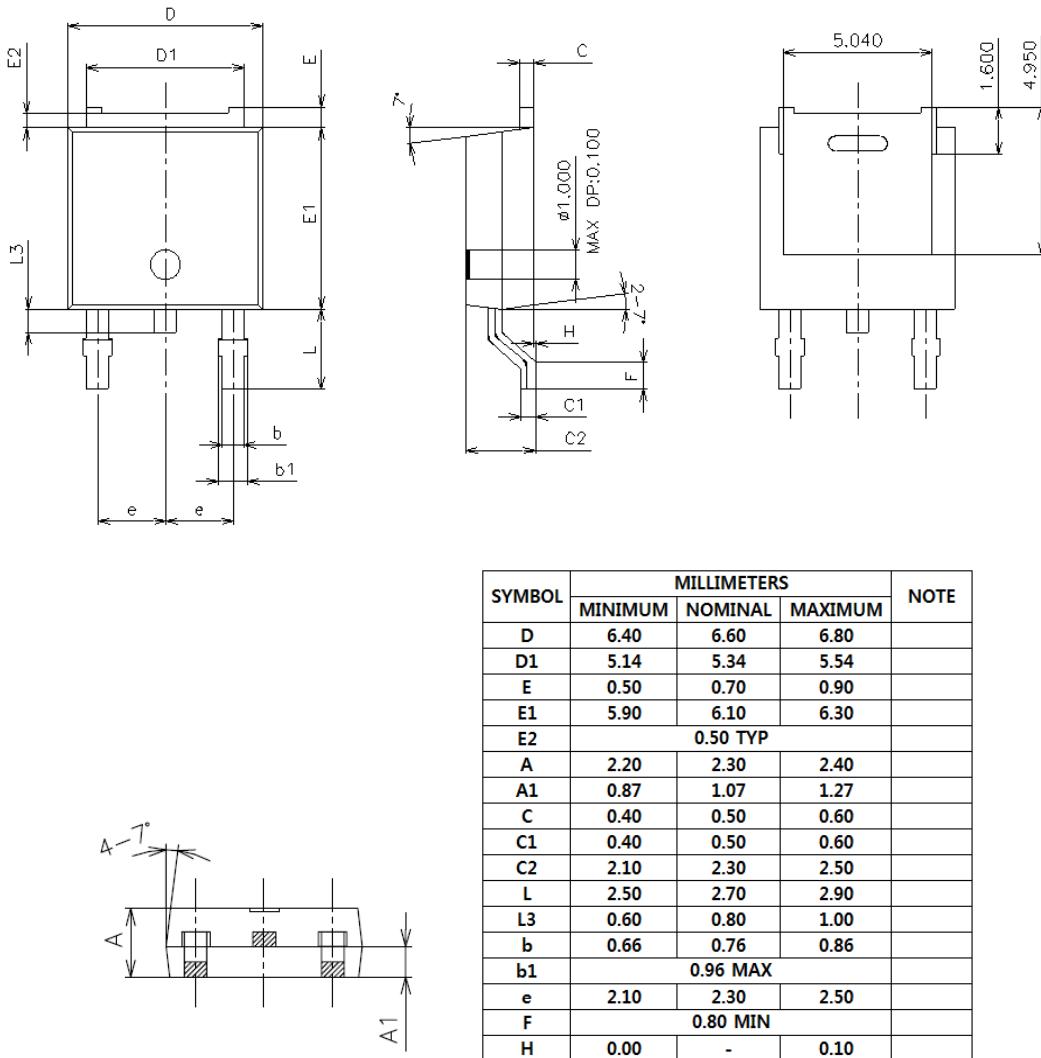
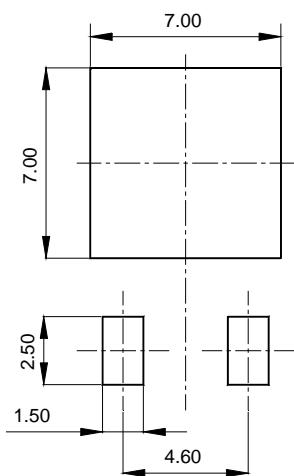


Fig. 14 Diode Reverse Recovery Time Test Circuit & Waveform



**Outline Dimension**

unit: mm

**Recommended Land Pattern [unit: mm]**

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